

**Amendments to the Claims:**

This listing of claims replaces all prior versions and listings of claims in the application:

**Listing of Claims:**

1. (Previously presented) A storage apparatus comprising:  
an enclosure;  
a printed circuit board fixed to the enclosure; and  
an electrical connector overmolded to the enclosure and in electrical communication with the printed circuit board.
2. (Previously presented) The storage apparatus of claim 1, wherein the electrical connector is overmolded with a material comprising a polymer.
3. (Previously presented) The storage apparatus of claim 1, wherein the electrical connector comprises a plurality of connector leads that are electrically coupled to contact pads of the printed circuit board.
4. (Previously presented) The storage apparatus of claim 1, wherein the electrical connector comprises a housing surrounding a plurality of conductive pins, the housing having an upper wall located above the conductive pins, an intermediate wall for supporting the conductive pins, and a lower wall located below the conductive pins.

5. (Previously presented) The storage apparatus of claim 4, wherein the electrical connector is overmolded to the upper wall, the lower wall, and the intermediate wall.

6. (Previously presented) The storage apparatus of claim 3, wherein the printed circuit board is fixed to the enclosure with fasteners.

7. (Previously presented) The storage apparatus of claim 6, wherein the fasteners compressingly engage the contact pads against the connector leads forming a resilient electrical connection.

8. (Previously presented) The storage apparatus of claim 1, wherein the enclosure comprises a protuberant feature extending into the overmolded section.

9. (Previously presented) The storage apparatus of claim 8, wherein the protuberant feature comprises a material that is the same as a material of the enclosure.

10. (Previously presented) The storage apparatus of claim 8, wherein the protuberant feature comprises a cylindrical post.

11. (Previously presented) The storage apparatus of claim 8, wherein the protuberant feature defines a notch.

12. (Withdrawn) A method comprising:

providing an enclosure;

overmolding an electrical connector to the enclosure; and

attaching a printed circuit board to the enclosure that operably engages the electrical connector.

13. (Withdrawn) The method of claim 12, wherein the overmolding step is characterized by injection molding.

14. (Withdrawn) The method of claim 12, wherein the overmolding step is characterized by using a polymer material.

15. (Withdrawn) The method of claim 12, wherein the attaching step is characterized by using fasteners.

16. (Withdrawn) The method of claim 14, wherein the fastening step is characterized by forcing contact pads of the printed circuit board to operably compress connector leads of the electrical connector.

17. (Withdrawn) The method of claim 12 wherein the overmolding step is characterized by extending a protuberant portion of the enclosure into the overmolding section.

18. (Withdrawn) The method of claim 17, wherein the overmolding step is characterized by the protuberant portion defining a notch.

19. (Currently amended) A storage apparatus comprising:  
an enclosure supporting a printed circuit board; and  
means for coupling an electrical connector to the printed circuit board for operably engaging the printed circuit board and [[to]] providing structural integrity to the electrical connector.

20. – 21. (Canceled)

22. (Previously presented) An electronic device comprising an enclosure and a printed circuit board coupled with a connector for electrically connecting the electronic device to an external device, wherein the connector is attached to the enclosure with an overmold section.

23. (Previously presented) The device of claim 22 wherein the printed circuit board is attached to the enclosure with a fastener that compressingly engages the printed circuit board against the connector.

24. (Previously presented) The device of claim 22 wherein the printed circuit board compressingly engages against the connector making a solderless electrical connection.

25. (Previously presented) The device of claim 22 wherein the overmold section contactingly engages a housing surrounding a plurality of conductive pins of the connector.

26. (Previously presented) The device of claim 22 wherein the enclosure defines a protuberant feature that is encompassed by the overmold section.